

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to:
Assistant Commissioner for Patents
Washington, D.C. 20231

7-
PATENT
Attorney Docket No. 16301-040300
Client Ref. No.
AMAT/4142/PDD/LOW K/JW

On 5-8-02

TOWNSEND and TOWNSEND and CREW LLP

By: Linda Sheffer



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

Hari Ponnekanti et al.

Application No.: 09/502,126

Filed: February 10, 2000

For: A PROCESS AND AN
INTEGRATED TOOL FOR LOW K
DIELECTRIC DEPOSITION
INCLUDING A PECVD CAPPING
MODULE

Examiner: Bret Chen

Art Unit: 1762

AMENDED RESPONSE TO
RESTRICTION REQUIREMENT AND
PRELIMINARY AMENDMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

In reply to the Notice of Non-Compliant Amendment dated April 8, 2002, the following is reproduced below in order to correct the informalities noted by the Examiner.

In response to the Office Action mailed September 25, 2001 requiring an election of the invention to be examined, reconsideration of this application is respectfully requested in light of the following election, remarks and amendments. A petition for a five month extension of time accompanies this response.

Election of Invention

The Examiner has indicated that restriction to one of the following inventions is required under 35 U.S.C. § 121:

- Group I. Claims 1-22, drawn to an apparatus, classified in Class 118, subclass 719.
- Group II. Claims 23-61, drawn to a method, classified in class 427, subclass 226.

RECEIVED

MAY 28 2002

TC 1700

COPY OF PAPERS
ORIGINALLY FILED

#11/B
Hada
5/31/02
entered in
part
8/1/02

In response to the restriction requirement, Applicants hereby elect Group I drawn to claims 1-22 without traverse, and cancel the non-elected Group II claims (claims 23-61).

Preliminary Amendments

Prior to examination of the above-referenced application, please enter the following amendments.

IN THE SPECIFICATION:

Please replace the paragraph beginning at page 4, line 10, with the following rewritten paragraph:

B2 --Figure 1 illustrates a vacuum cluster tool 10 having multiple single substrate processing chambers 12 mounted on a centralized vacuum chamber, called a transfer chamber 18, for transferring substrates from a substrate cassette located in one or more load lock chambers 20, to one or more process chambers 12. This particular tool is shown to accommodate up to four (4) single substrate processing chambers 12 positioned radially about the transfer chamber. A cluster tool similar to that shown in Figure 1 is available from Applied Materials, Inc. of Santa Clara, California. The transfer of the substrates between the process chambers 12 is typically managed by a substrate handling module 16 located in a central transfer chamber 8. After the substrates are processed, they are moved back through the load lock chamber 20 and into substrate cassettes where the 20 substrates can be moved to the next system for additional processing. Various processes, such as physical vapor deposition (PVD), chemical vapor deposition (CVD), etch, can be performed in the process chambers 12.--

Please replace the paragraph beginning at page 5, line 22, with the following rewritten paragraph:

B2 --The apparatus of the invention may further comprise one or more substrate cooling stations disposed in the loadlock chamber connected to the transfer chamber. The capping module preferably has a substrate handling member with at least one substrate handling blade and further includes a substrate indexing device for indexing multiple substrates and a multi-slot preheating module for preheating substrates prior to deposition of the capping layer. Each PECVD chamber preferably has two processing regions, each processing region having a heated pedestal, a gas distribution assembly, vacuum pumping assembly, and independent RF power and temperature